

2-Phase, D-CAP+™ Step-Down Controller for VR12.6 V_{CPU}

1 Features

- Intel® VR12.6 PWM Specification serial VID (SVID) compliant
- 1- or 2-phase operation
- Full VR12.6 mobile feature set including digital current monitor, PS3 and PS4 operation
- 8-Bit DAC with 0.50-V to 2.30-V output range
- Optimized efficiency at light and heavy loads
- 8 independent levels of overshoot reduction (OSR) and undershoot reduction (USR)
- Driverless configuration for efficient high-frequency switching
- Supports discrete, power block, Power Stage or DrMOS MOSFET implementations
- Accurate, adjustable voltage positioning
- 300-kHz to 1.5-MHz frequency selections
- Patented AutoBalance phase balancing
- Selectable 8-level current limit
- 4.5-V to 28-V conversion voltage range
- Small, 4 × 4, 32-pin, QFN PowerPAD™ integrated circuit package

2 Applications

- VR12.6 VCPU applications for
 - Adapter
 - Battery
 - NVDC
 - 5-V or 12-V rails

3 Description

The TPS51624 is a driverless, fully SVID compliant, VR12.6 step-down controller. Advanced control features such as D-CAP+ architecture with overlapping pulse support undershoot reduction (USR) and overshoot reduction (OSR) provide fast transient response, lowest output capacitance and high efficiency. The TPS51624 also supports single-phase operation in CCM or DCM for light-load efficiency. The TPS51624 integrates the full complement of VR12.6 I/O features including VR_READY (PGOOD), ALERT and VR_HOT. The SVID interface address allows programming from 0 to 7. In PS4, the quiescent power consumption of controller is typical 0.25 mW. Adjustable control of VCPU slew rate and voltage positioning round out the VR12.6 features. Paired with the new TPS51604 FET gate driver, the solution delivers exceptionally high speed and low switching loss. The TPS51624 works with selected TI Power Stage™ products for optimum efficiency as well as DrMOS products.

The TPS51624 package is a space saving, thermally enhanced 32-pin QFN that operates from -40°C to 105°C.

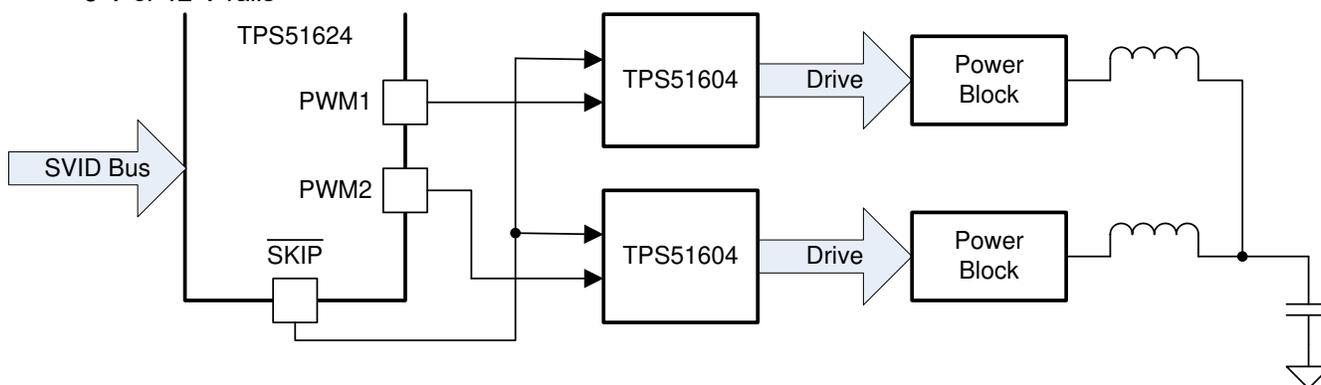


Figure 3-1. Simplified Schematic



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
June 2022	*	Initial Release

5 Device and Documentation Support

5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

5.3 Trademarks

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5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

6 Mechanical, Packaging, and Orderable Information

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS51624RSMR	Active	Production	VQFN (RSM) 32	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	TPS 51624
TPS51624RSMR.A	Active	Production	VQFN (RSM) 32	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	TPS 51624
TPS51624RSMT	Active	Production	VQFN (RSM) 32	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	TPS 51624
TPS51624RSMT.A	Active	Production	VQFN (RSM) 32	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	TPS 51624

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

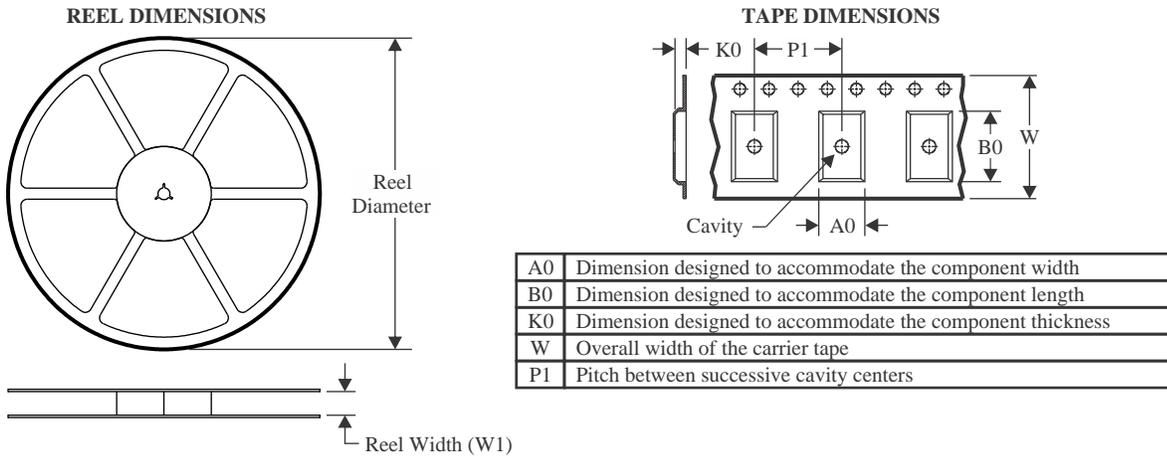
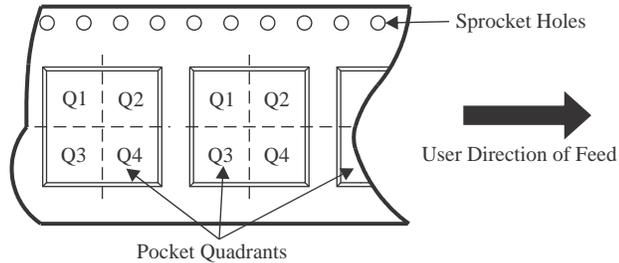
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

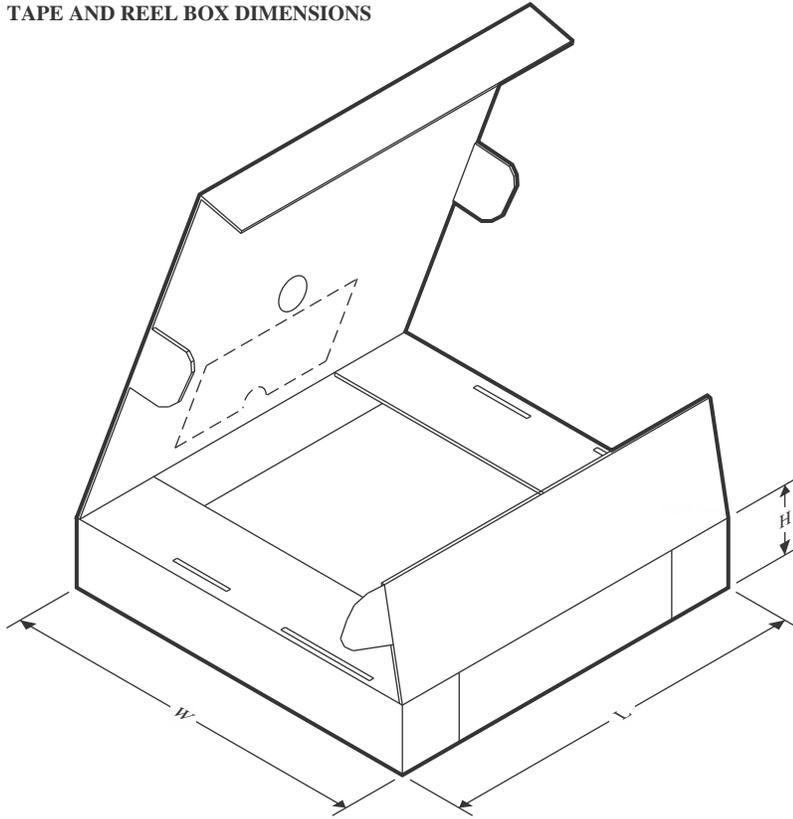
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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS51624RSMR	VQFN	RSM	32	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
TPS51624RSMT	VQFN	RSM	32	250	180.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS51624RSMR	VQFN	RSM	32	3000	367.0	367.0	35.0
TPS51624RSMT	VQFN	RSM	32	250	210.0	185.0	35.0

GENERIC PACKAGE VIEW

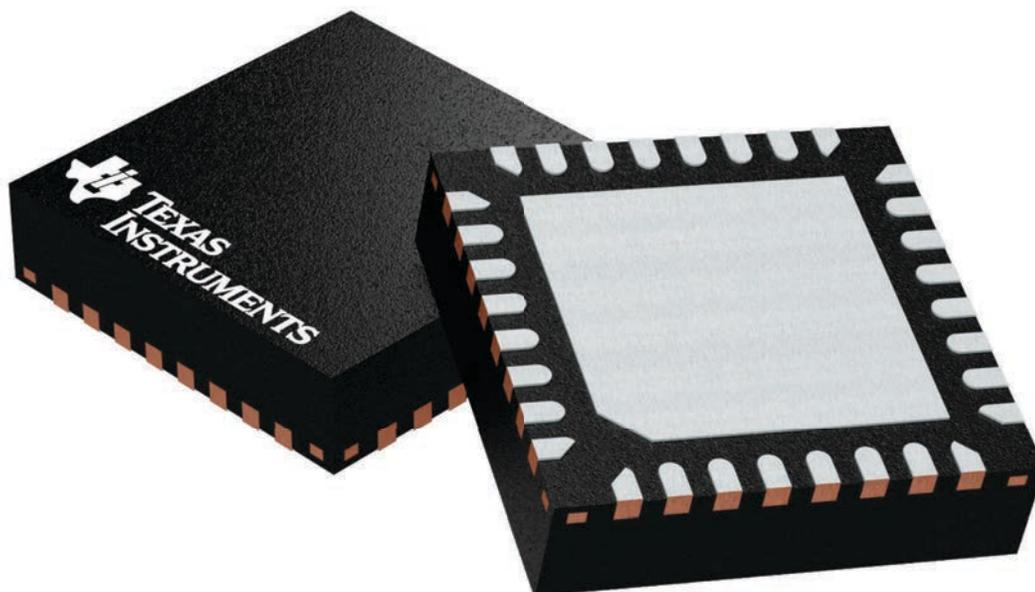
RSM 32

VQFN - 1 mm max height

4 x 4, 0.4 mm pitch

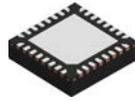
PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



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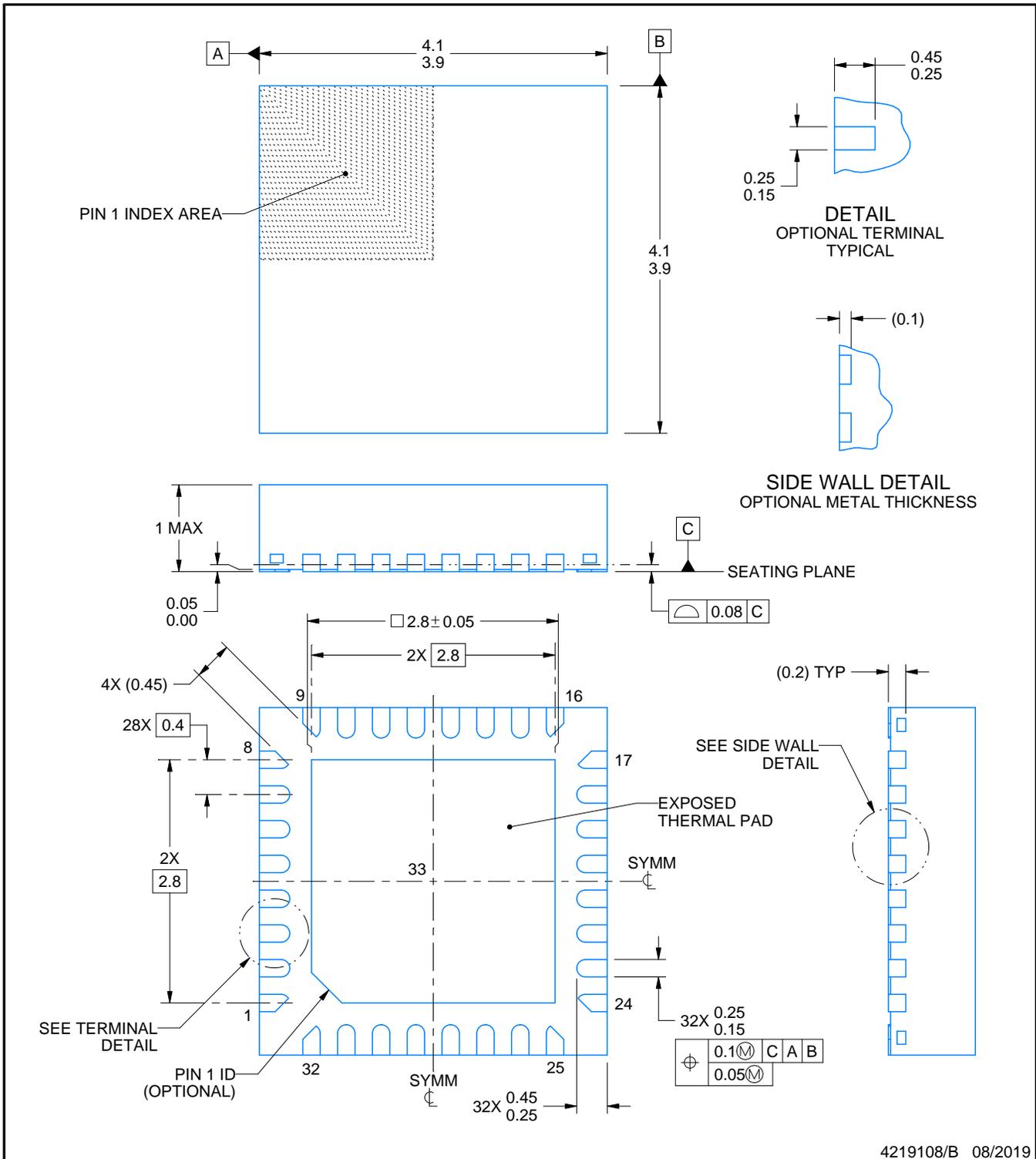
RSM0032B



PACKAGE OUTLINE

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

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